



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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2SD1269

Silicon NPN epitaxial planar type

For power switching

Complementary to 2SB0944

■ Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Large collector current I_C
- Full-pack package which can be installed to the heat sink with one screw.

■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	130	V
Collector-emitter voltage (Base open)	V_{CEO}	80	V
Emitter-base voltage (Collector open)	V_{EBO}	7	V
Collector current	I_C	4	A
Peak collector current	I_{CP}	8	A
Collector power dissipation	P_C	35	W
	$T_a = 25^\circ\text{C}$	2.0	
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

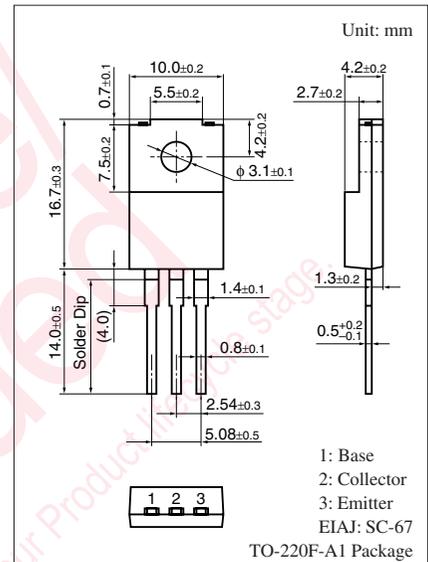
■ Electrical Characteristics $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

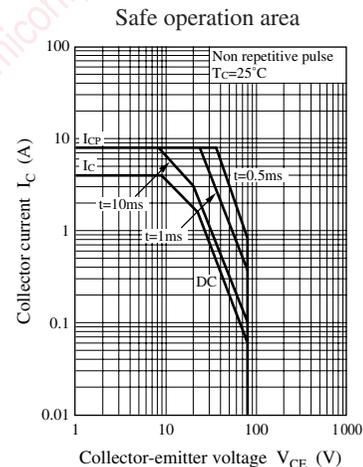
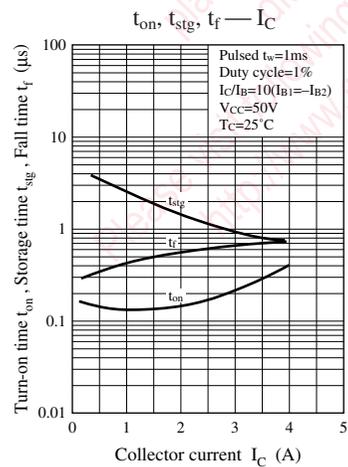
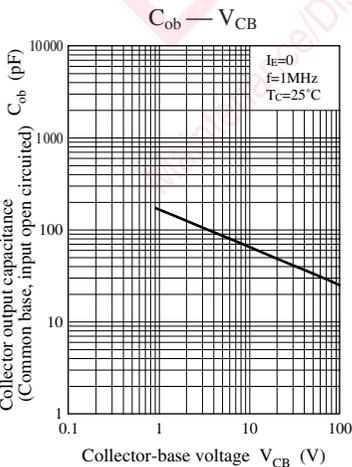
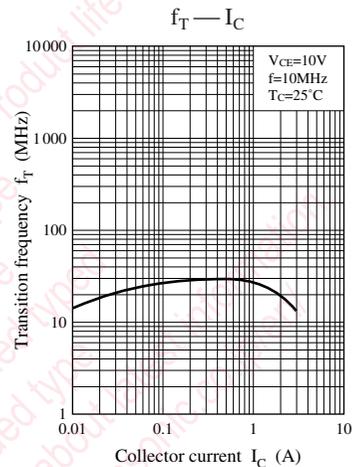
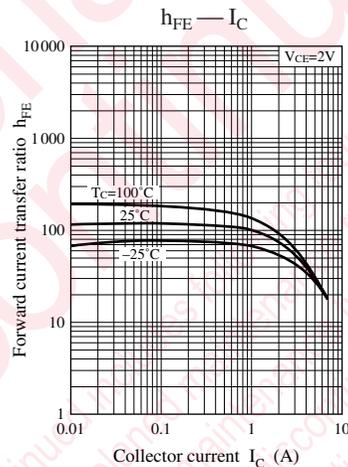
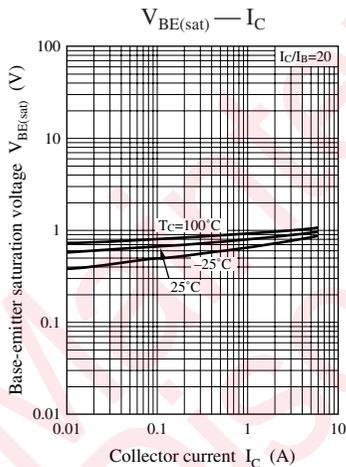
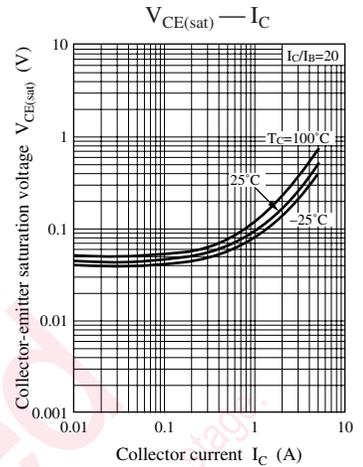
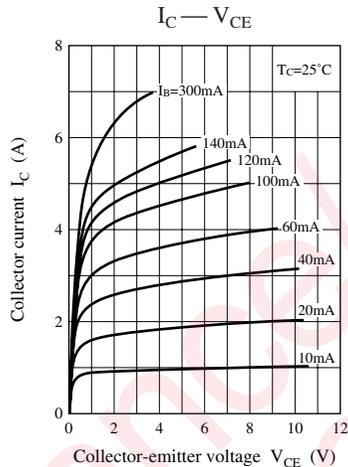
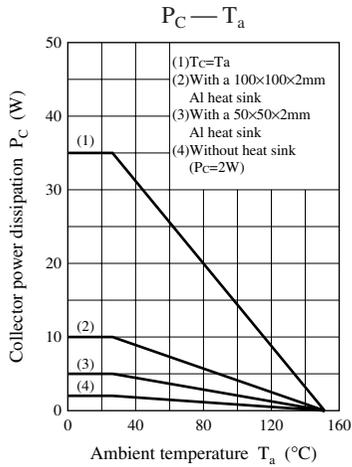
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 10\text{ mA}, I_B = 0$	80			V
Collector-base cut-off current (Emitter open)	I_{CBO}	$V_{CB} = 100\text{ V}, I_E = 0$			10	μA
Emitter-base cut-off current (Collector open)	I_{EBO}	$V_{EB} = 5\text{ V}, I_C = 0$			50	μA
Forward current transfer ratio	h_{FE1}	$V_{CE} = 2\text{ V}, I_C = 0.1\text{ A}$	45			—
	h_{FE2}^*	$V_{CE} = 2\text{ V}, I_C = 1\text{ A}$	60		260	
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 3\text{ A}, I_B = 0.15\text{ A}$			0.5	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C = 3\text{ A}, I_B = 0.15\text{ A}$			1.5	V
Transition frequency	f_T	$V_{CE} = 10\text{ V}, I_C = 0.5\text{ A}, f = 10\text{ MHz}$		30		MHz
Turn-on time	t_{on}	$I_C = 1\text{ A}, I_{B1} = 0.1\text{ A}, I_{B2} = -0.1\text{ A}$		0.5		μs
Storage time	t_{stg}	$V_{CC} = 50\text{ V}$		2.5		μs
Fall time	t_f			0.15		μs

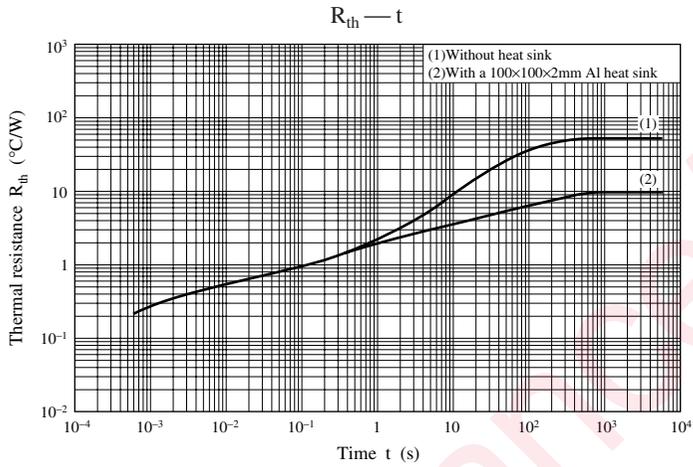
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	R	Q	P
h_{FE2}	60 to 120	90 to 180	130 to 260







Maintenance/Discontinued includes following four Product lifecycle stage.
planned maintenance type
maintenance type
planned discontinued type
discontinued type
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